



TTM Technologies Interconnect Solutions is a leader in quick-turn, technically advanced PCB solutions. We offer a wide range of Printed Circuit Board (PCB) products, including Conventional, High-Density Interconnect (HDI), Ultra-HDI, Flexible and Rigid-Flex, Backplane, and Substrate-like PCBs. We offer value-added services to support our Aerospace, Defense, and Commercial customers.

Conventional PCB

We have a strong history of delivering highly reliable PCBs to our customers. Our comprehensive support spans every stage of the product lifecycle, complemented by an extensive range of capabilities—including multi-layer designs up to 60 layers, conventional HDI, and precision back drilling.

High-Density Interconnect PCB

Our HDI solutions deliver exceptional performance and high-density features tailored for advanced applications. Key attributes include laser microvias, sequential lamination structures, fine line technology, and high-performance thin materials, enabling greater functionality and integration. Our multi-layer copper-filled stacked microvias create a structure that allows even more complex interconnections.

Flex/Rigid-Flex PCB

Our flex and rigid-flex solutions offer our customers industry-leading manufacturing services that support emerging technology trends for the entire product life cycle. We provide reliable integration of multiple rigid PCB assemblies into a single PCB module, supporting assembly, resulting in space/weight savings and mechanical stability.

Thermal Management

Thermal management is essential to maintaining component durability and performance in the field. Higher frequencies, increased data rates, and the high current required by inverters and motor drives have dramatically increased the need for heat dispensation. We offer a number of thermal management solutions, including via farms, heatsinks/pallets, heatsink coins, embedded coins, patented e-coin, Press-Fit Coin (PFC), metal inlay, and solder or adhesive attach.

Substrate-Like (SLP) PCB

The next generation of semiconductor packaging solutions includes our HyperBGA® and CoreEZ®, providing our customers SLPs that meet the low-loss, high-speed needs for high-reliability applications.

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■ CoreEZ®

CoreEZ® semiconductor packaging uses the HyperBGA® manufacturing platform to offer a thin core build-up flip-chip package with very dense core vias using a cost-sensitive material set. The core via density provides 199-micron via-to-via core pitch, resulting in a coreless structure. The result is a highly cost-effective solution that allows total stripline signal layers on both sides of the core.